



TJM4558

WIDE BANDWIDTH DUAL BIPOLAR OPERATIONAL AMPLIFIERS

- INTERNALLY COMPENSATED
- SHORT-CIRCUIT PROTECTION
- GAIN AND PHASE MATCH BETWEEN AMPLIFIER
- LOW POWER CONSUMPTION
- PIN TO PIN COMPATIBLE WITH MC1458/LM358
- GAIN BANDWIDTH PRODUCT (at 100kHz) 5.5MHz

DESCRIPTION

The TJM4558 is a high performance monolithic dual operational amplifier.

The circuit combines all the outstanding features of the MC1458 and, in addition possesses three times the unity gain bandwidth of the industry standard.

ORDER CODE

Part Number	Temperature Range	Package		
		N	D	P
TJM4558C	0°C, +70°C	•	•	•
TJM4558I	-40°C, +105°C	•	•	•

Example : TJM4558CN

N = Dual in Line Package (DIP)

D = Small Outline Package (SO) - also available in Tape & Reel (DT)

P = Thin Shrink Small Outline Package (TSSOP) - only available in Tape & Reel (PT)



N
DIP8
(Plastic Package)

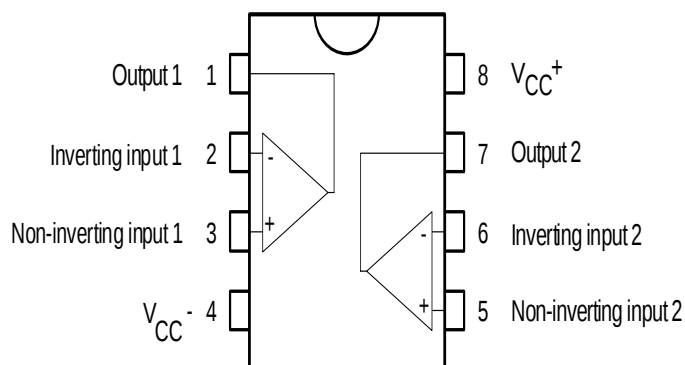


D
SO8
(Plastic Micropackage)

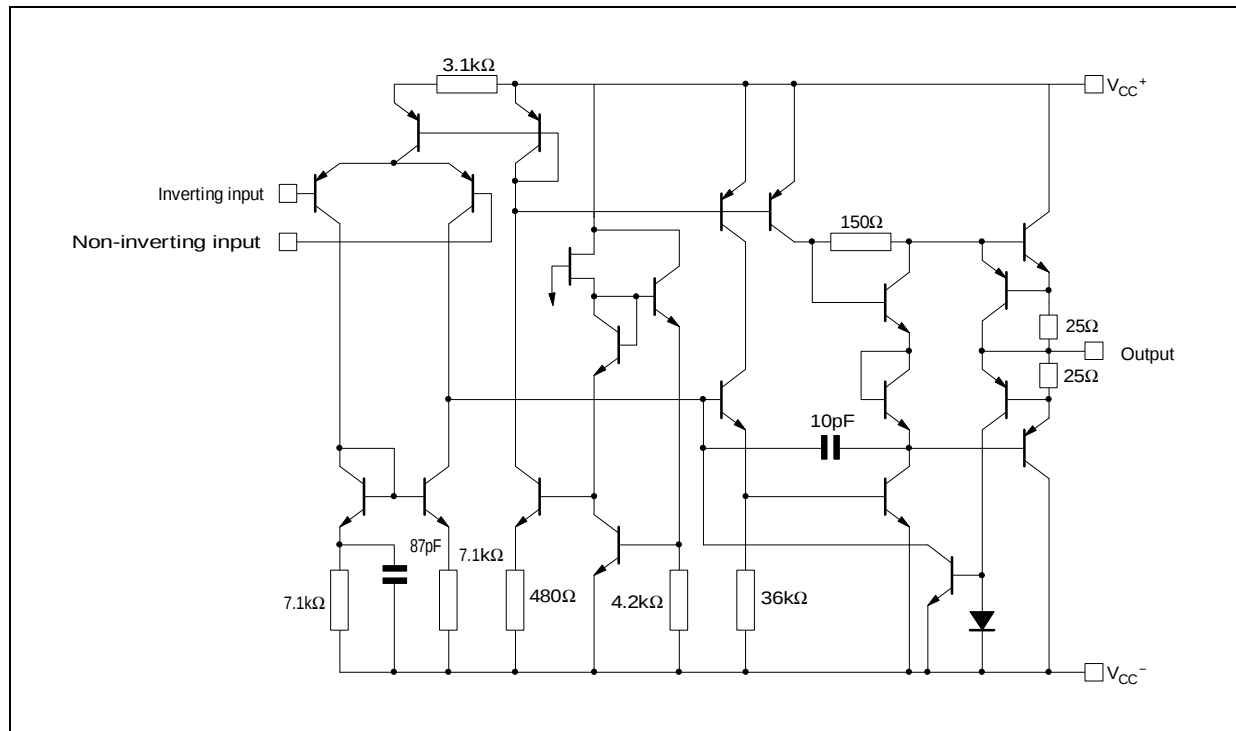


P
TSSOP8
(Thin Shrink Small Outline Package)

PIN CONNECTIONS (top view)



SCHEMATIC DIAGRAM (1/2 TJM4558)



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	TJM4558I	TJM4558C	Unit
V_{CC}	Supply Voltage	± 22		V
V_i	Input Voltage	± 15		V
V_{id}	Differential Input Voltage	± 30		V
P_{tot}	Power Dissipation	680		mW
	Output Short Circuit Duration	Infinite		
T_{oper}	Operating Free-Air Temperature Range	-40 to +105	0 to +70	$^{\circ}\text{C}$
T_{stg}	Storage Temperature	-65 to +150		$^{\circ}\text{C}$

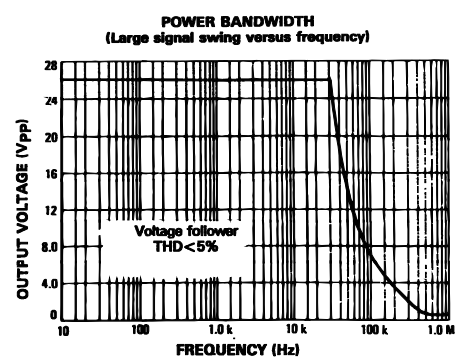
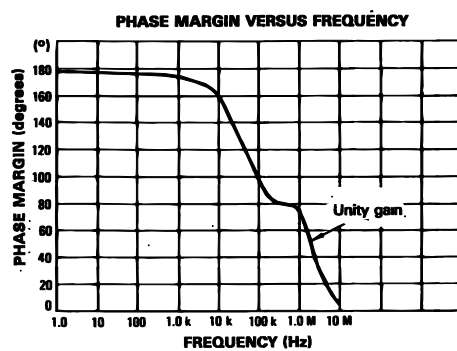
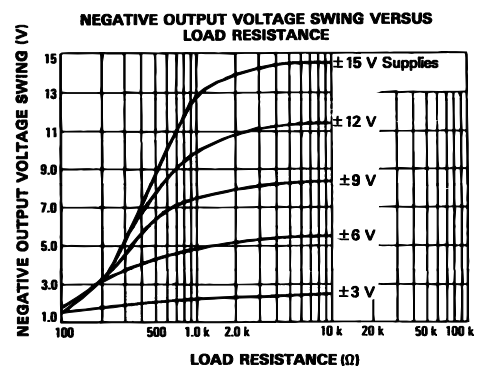
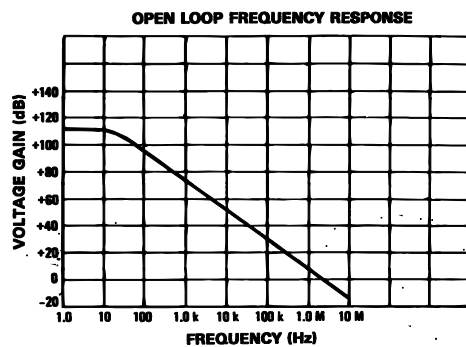
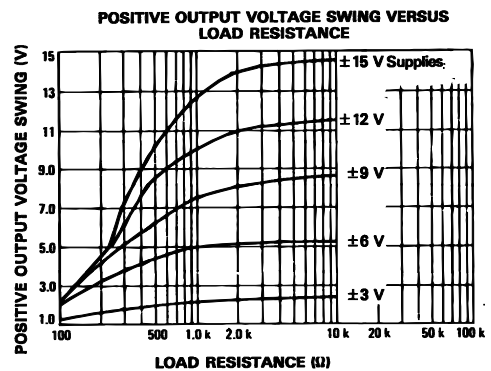
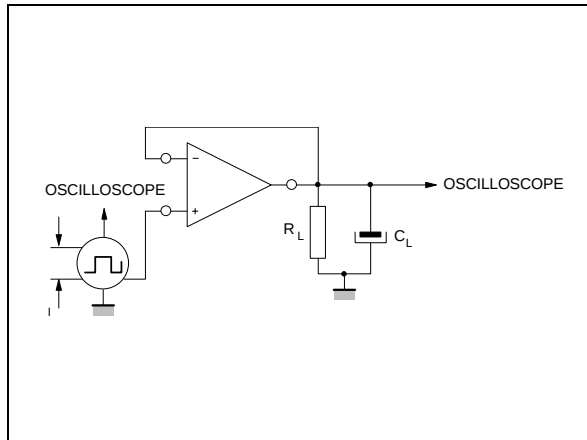
ELECTRICAL CHARACTERISTICS

$V_{CC} = \pm 15\text{V}$, $T_{amb} = 25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{io}	Input Offset Voltage ($R_s \leq 10\text{k}\Omega$) $T_{amb} = +25^{\circ}\text{C}$ $T_{min} \leq T_{amb} \leq T_{max}$		1	5 6	mV
I_{io}	Input Offset Current $T_{amb} = +25^{\circ}\text{C}$ $T_{min} \leq T_{amb} \leq T_{max}$		20 40	100	nA
I_{ib}	Input Bias Current $T_{amb} = +25^{\circ}\text{C}$ $T_{min} \leq T_{amb} \leq T_{max}$		50 100	400	nA
A_{vd}	Large Signal Voltage Gain ($R_L = 2\text{k}\Omega$, $V_o = \pm 10\text{V}$) $T_{amb} = +25^{\circ}\text{C}$ $T_{min} \leq T_{amb} \leq T_{max}$	50 25	200		V/mV

Symbol	Parameter	Min.	Typ.	Max.	Unit
SVR	Supply Voltage Rejection Ratio ($R_S \leq 10k\Omega$) $T_{amb} = +25^\circ C$ $T_{min} \leq T_{amb} \leq T_{max}$		90 77		dB
I_{CC}	Supply Current, all amplifiers, no load $T_{amb} = +25^\circ C$ $T_{min} \leq T_{amb} \leq T_{max}$		2.3 4	4.5	mA
V_{icm}	Input Common Mode Voltage Range $T_{amb} = +25^\circ C$ $T_{min} \leq T_{amb} \leq T_{max}$	± 12 ± 12			V
CMR	Common-mode Rejection Ratio ($R_S \leq 10k\Omega$) $T_{amb} = +25^\circ C$ $T_{min} \leq T_{amb} \leq T_{max}$		90 70		dB
I_{OS}	Output Short Circuit Current	10	20		mA
V_O	Output Voltage Swing $T_{amb} = +25^\circ C$ $T_{min} \leq T_{amb} \leq T_{max}$ $R_L = 10k\Omega$ $R_L = 2k\Omega$ $R_L = 10k\Omega$ $R_L = 2k\Omega$	± 12 ± 10 ± 12 ± 10	± 14 ± 13		V
SR	Slew Rate ($V_i = \pm 10$, $R_L = 2k\Omega$, $C_L = 100pF$, $T_{amb} = 25^\circ C$, unity gain)		2.2		V/ μs
t_r	Rise Time ($V_i = \pm 20mV$, $R_L = 2k\Omega$, $C_L = 100pF$, $T_{amb} = 25^\circ C$, unity gain)		0.3		μs
K_{OV}	Overshoot ($V_i = \pm 20mV$, $R_L = 2k\Omega$, $C_L = 100pF$, $T_{amb} = 25^\circ C$, unity gain)		15		%
R_i	Input Resistance	0.3	2		$M\Omega$
C_i	Input Capacitance		1.4		pF
R_O	Output Resistance		75		Ω
B	Unity Gain Bandwidth		2.8		MHz
GBP	Gain Bandwidth Product ($V_i = 10mV$, $R_L = 2k\Omega$, $C_L = 100pF$, $f = 100kHz$, $T_{amb} = 25^\circ C$)		5.5		MHz
THD	Total Harmonic Distortion ($f = 1kHz$, $A_v = 20dB$, $R_L = 2k\Omega$, $V_O = 2V_{pp}$, $C_L = 100pF$, $T_{amb} = 25^\circ C$)		0.008		%
e_n	Equivalent Input Noise Voltage ($R_S = 100\Omega$, $f = 1kHz$)		12		$\frac{nV}{\sqrt{Hz}}$
V_{O1}/V_{O2}	Channel Separation		120		dB

TRANSIENT RESPONSE TEST CIRCUIT



PACKAGE MECHANICAL DATA

Plastic DIP-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A		3.3			0.130	
a1	0.7			0.028		
B	1.39		1.65	0.055		0.065
B1	0.91		1.04	0.036		0.041
b		0.5			0.020	
b1	0.38		0.5	0.015		0.020
D			9.8			0.386
E		8.8			0.346	
e		2.54			0.100	
e3		7.62			0.300	
e4		7.62			0.300	
F			7.1			0.280
I			4.8			0.189
L		3.3			0.130	
Z	0.44		1.6	0.017		0.063

The diagram illustrates the mechanical specifications of a Plastic DIP-8 package through three views: top, side, and bottom. The top view shows the package body with pins extending from the top and bottom edges. Dimensions labeled include A (total height), a1 (pin height from body), B (pin spacing), B1 (pin width), b (pin width), b1 (pin thickness), D (total width), e (pin pitch), e3 (body width), e4 (body width), F (pin length), I (pin length), L (body length), and Z (lead thickness). The side view shows the package profile with dimensions E (body length) and b1 (pin thickness). The bottom view shows the package footprint with pins extending downwards, labeled with pin numbers 1, 4, 5, and 8 to indicate pin 1 orientation.

P001F

PACKAGE MECHANICAL DATA

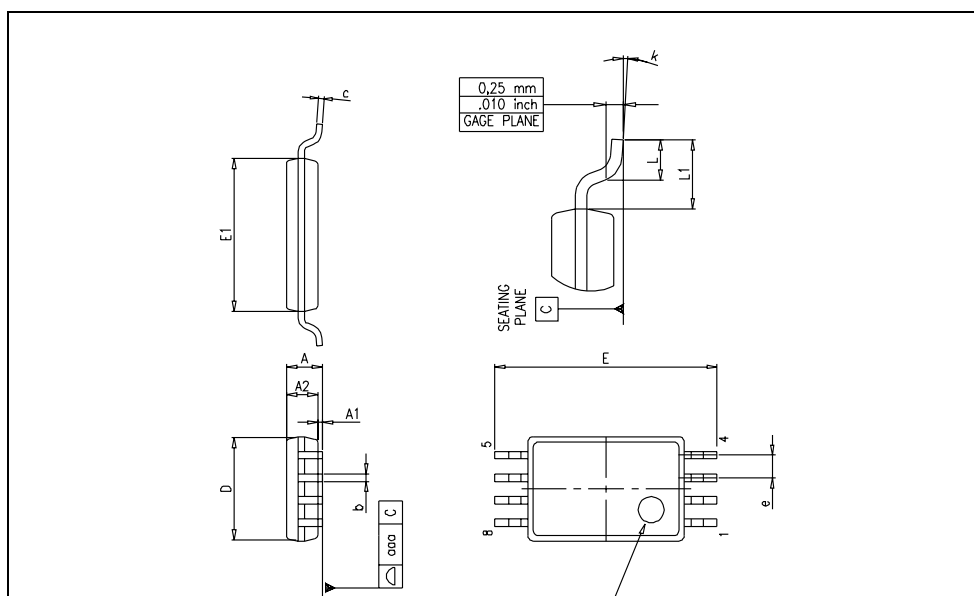
SO-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.04		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.150		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.1			0.04

0016023/C

PACKAGE MECHANICAL DATA

TSSOP8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.008
D	2.90	3.00	3.10	0.114	0.118	0.122
E	6.20	6.40	6.60	0.244	0.252	0.260
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.65			0.0256	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1			0.039	



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